

## Economy Vapour Phase Soldering System for individual and series production



### Features

- Ideal for individual and series production as well as rework applications
- 2-Chamber Stand alone Batch-Soldering-Machine
- Easy operation through touch screen TFT monitor
- Program storage incl. standard soldering programs
- Soldering automatic and Heat Level adjustment
- TE-Option; two thermocouple adapter for profile recording with profiler outside
- Energy management system for lowest energy consumption incl. standby mode
- No compressed air necessary
- Lowest fluid consumption due to internal heat exchanger and fluid recovery
- Maintenance free transport unit (TPS, **Patented**)

### Standard Equipment / Specification

- Comfortable operation with Touch Screen Monitor
- Automatic carrier in- and output
- 2 process chambers with internal air-lock separation
- Observation window into process chamber
- Integrated illumination of the soldering chamber
- Overheating prevention through monitoring of cooling water and heating chamber temperature
- Automatic fluid filtering and level monitoring
- Integrated cooling blower for board cooling
- Integrated heat exchanger and fluid recovery system
- Variable energy level set-up including program storage
- Automatic or time controlled soldering process incl. work piece carrier compensation (**Patented**)
- Maintenance free transportation system (**Patented**)

### Options

- Adapter for double sided PCB board
- ReSy, a device for repair of QFP's and BGA's, (**Patented**)
- Stainless steel grid for work piece carrier
- Cooling device for closed loop machine cooling
- TE-Option (2 channels) for external profile monitoring

### Overview

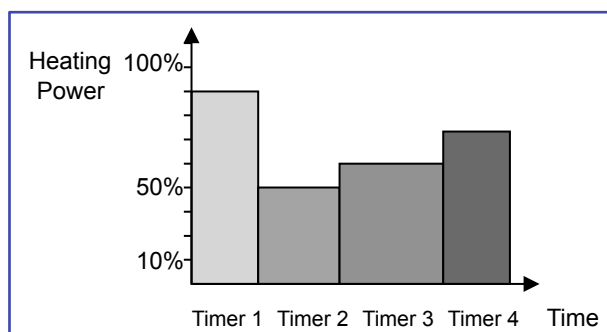
The SV 360 is a vapour phase soldering system that is used for a broad range of soldering applications.

The 2 chamber system in combination with the frontloading allows a comfortable operation. This supports high operational quality standards as well as high throughput.

### Modes of operation

#### Heat Level Mode (HL-Mode)

A simple variation of vapour phases soldering, generates different, nearly linear temperature profiles. Energy transfer is controlled by adjustable heating power.



### Solder Automatic

For the optimization of the solder-process the integrated standard-solder-automatic can be activated in addition. This automatically controls the adaptation of the solder time.

### Technical Data SV 360

Width	1,450mm
Depth	1,000 mm
Height	1,400 mm
Weight	310 kg
max. PCB size	560 x 360 x 80 mm
Soldering fluid filling (min.)	10 kg
Water connection	1/2"
Max. heating capacity	5.2 kW
Ø power consumption	2.8 kWh
Power supply / Main fuse	400 VAC, 6 kW / 16 A, Type "gL" or "C"

- Technical changes reserved -